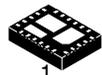


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

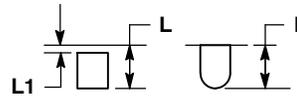
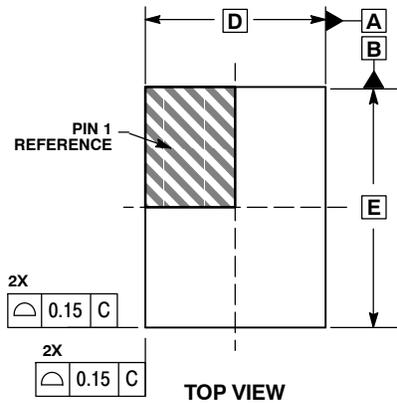
ON Semiconductor®



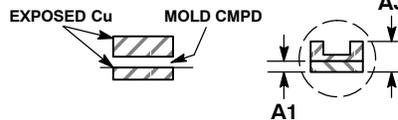
SCALE 2:1

QFN22, 3x4, 0.5P
CASE 485AT-01
ISSUE B

DATE 17 SEP 2008



DETAIL A
OPTIONAL
CONSTRUCTIONS

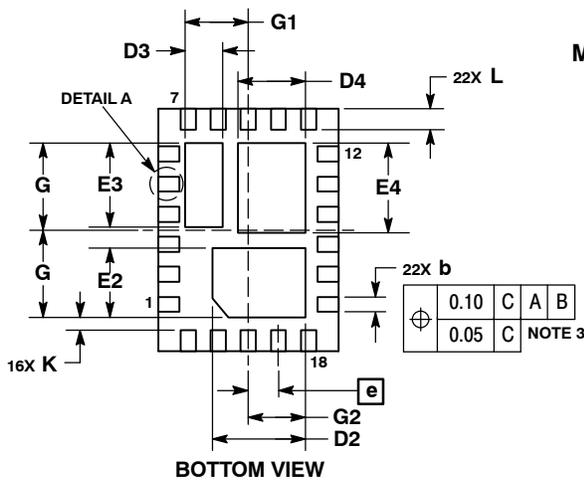
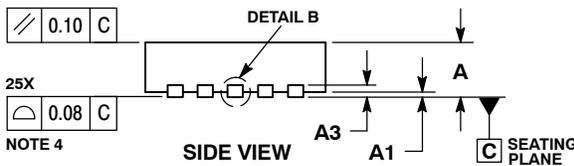


DETAIL B
OPTIONAL
CONSTRUCTIONS

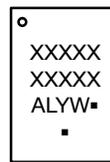
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.025	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
D	3.00 BSC		
D2	1.45	1.50	1.55
D3	0.52	0.57	0.62
D4	1.02	1.07	1.12
E	4.00 BSC		
E2	1.05	1.10	1.15
E3	1.30	1.35	1.40
E4	1.40	1.45	1.50
e	0.50 BSC		
K	0.25	---	---
L	0.30	0.325	0.35
L1	---	---	0.15
G	1.35	1.40	1.50
G1	0.95	1.05	1.15
G2	0.855	0.885	0.915



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

A = Assembly Location

L = Wafer Lot

Y = Year

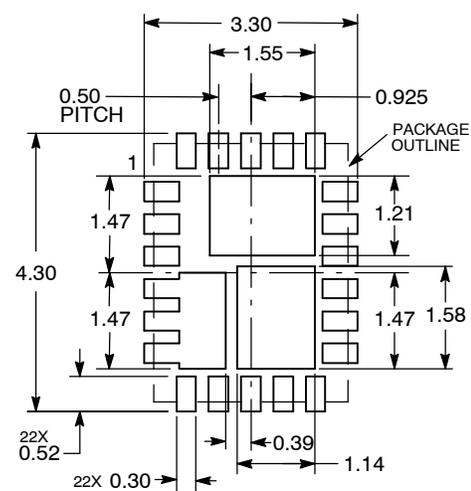
W = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN22, 3X4, 0.5 P	
		PAGE 1 OF 2

